

Material Content Data Sheet

RoHS | Halogen-Free

Sales Product Name	BSC009NE2LS5	**Issued**	4. July 2019
MA#	MA004645460		
Package	PG-TDSON-8-46	**Weight***	118.26 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	0.699	0.59	0.59	5908	5908
leadframe	inorganic material	phosphorus	7723-14-0	0.011	0.01		96	
	non noble metal	iron	7439-89-6	0.038	0.03		320	
	non noble metal	copper	7440-50-8	37.762	31.93	31.97	319299	319715
wire	non noble metal	copper	7440-50-8	0.021	0.02	0.02	176	176
encapsulation	organic material	carbon black	1333-86-4	0.087	0.07		735	
	plastics	epoxy resin	-	6.869	5.81		58086	
	inorganic material	silicondioxide	60676-86-0	36.521	30.88	36.76	308811	367632
leadfinish	non noble metal	tin	7440-31-5	1.452	1.23	1.23	12275	12275
plating	noble metal	silver	7440-22-4	0.166	0.14	0.14	1400	1400
solder	non noble metal	tin	7440-31-5	0.020	0.02		166	
	noble metal	silver	7440-22-4	0.025	0.02		208	
	non noble metal	lead	7439-92-1	0.939	0.79	0.83	7941	8315
heatspreader	inorganic material	phosphorus	7723-14-0	0.003	0.00		29	
	non noble metal	iron	7439-89-6	0.011	0.01		96	
	non noble metal	copper	7440-50-8	11.320	9.57	9.58	95718	95843
heat sink CLIP	inorganic material	phosphorus	7723-14-0	0.007	0.01		57	
	non noble metal	iron	7439-89-6	0.022	0.02		189	
	non noble metal	copper	7440-50-8	22.292	18.85	18.88	188490	188736
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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